

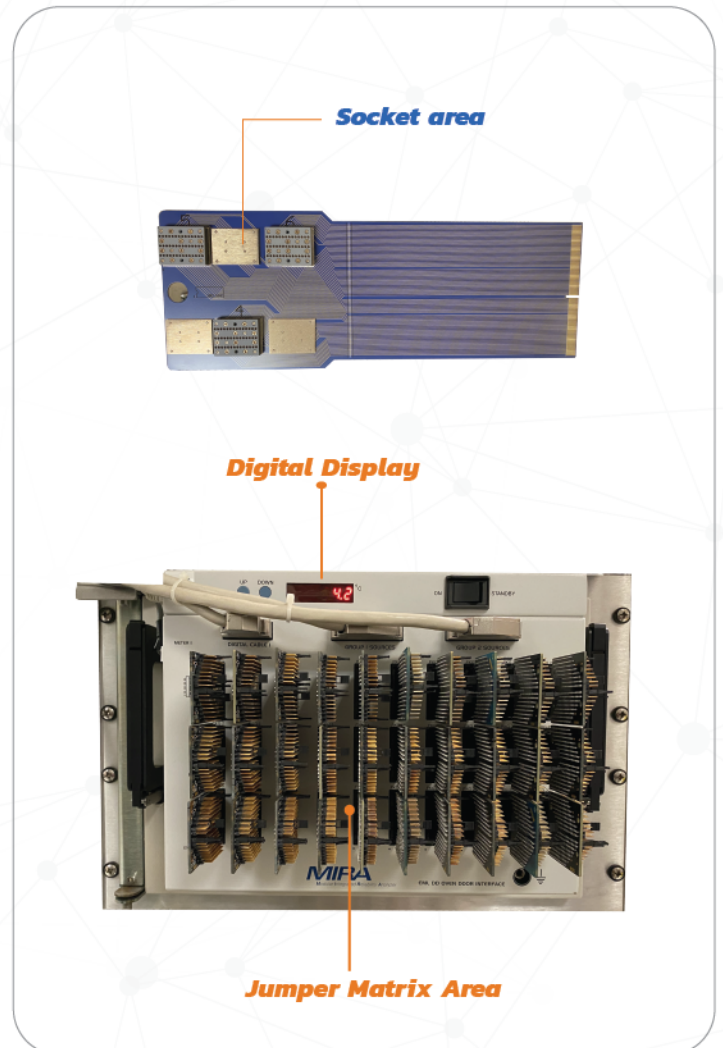
Next Generation

REAR-LOAD OVEN System



MIRA REAR LOAD OVEN ADVANTAGES:

- Reliable and versatile oven that supports unique applications
- 60 DUT capacity per oven with 5 DUT boards
- 450°C capable
- Independent connectivity matrix to support any bonding requirements
- Efficient testing throughput
- Digital oven temperature display per unit.
- Easy DUT board loading and unloading.
- Low power consumption.
- Field proven system with installation at major semiconductor companies.
- Less floor space than any other available system with up to 240 DUTs per rack.



Consult QualiTau for detailed specifications.

TESTING THE FUTURE